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Scuola di Dottorato in Ingegneria “Leonardo da Vinci”



**Corso di Dottorato di Ricerca in  
Ingegneria dell'Informazione**

**Tesi di Dottorato di Ricerca**

**Design of integrated mixed-signal IPs  
for automotive applications**

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# TABLE OF CONTENTS

Table of contents .....	3
Index of Figures.....	5
Index of Tables .....	8
Introduction .....	9
Chapter 1    Automotive Electronic systems challenges .....	11
1.1    Electronic systems drive innovation in automotive.....	11
1.2    Automotive electronic applications .....	14
1.2.1    Chassis & safety .....	14
1.2.2    Powertrain.....	19
1.2.3    Infotainment .....	22
1.3    Automotive challenges .....	23
Chapter 2    Implementation of a multi-purpose platform in BCD technology	29
2.1    Methodologies to face automotive challenges.....	29
2.2    Platform-based design methodology .....	31
2.3    Platform for automotive sensors.....	32
2.4    Application space .....	33
2.4.1    Angular rate sensor.....	34
2.4.2    Acceleration sensor .....	35
2.4.3    Magneto-resistive sensors .....	36
2.5    BCD Technology .....	38
2.6    Sensor platform overview.....	44
2.7    Dual axis accelerometer prototypization with ISIF .....	49
Chapter 3    Platform application space extension .....	55
3.1    ISIF Platform limits .....	55
3.2    Half-bridge driver design .....	56
3.2.1    MOS Gate drivers: operation principle .....	57
3.2.2    Mirror configuration gate driver.....	62

3.2.3	Digital control of the gate driver.....	65
3.2.4	Gate driver layout.....	68
3.2.5	Simulations & Measurements .....	68
3.3	ISIF extension to video projection systems .....	71
3.4	MOEMS technology and its applications .....	75
3.4.1	Micromachining techniques.....	76
3.4.2	Digital micromirror .....	77
3.4.3	Scanning micromirror .....	79
3.4.4	Electrostatic scanning micromirror specifications .....	82
3.5	High voltage micromirror driver design .....	84
3.5.1	Driver architectural choice.....	86
3.5.2	HV Driver design: top level definition .....	87
3.5.3	HV Driver specifications .....	89
3.5.4	HV Driver design analysis .....	90
1.	OPA First Stage .....	90
2.	OPA second stage .....	91
3.	CMFB .....	93
4.	Biasing, power down and protection circuitries.....	96
5.	Considerations on devices size .....	98
3.5.5	HV Driver simulations .....	102
3.5.6	HV Driver layout .....	108
	Conclusions.....	113

# INDEX OF FIGURES

Figure 1.1: Automotive Electronic segments [source: Bosch] .....	12
Figure 1.2: MCUs performances versus applications [source: Freescale].....	14
Figure 1.3: technologies enabling modern chassis .....	15
Figure 1.4: IMUs work by detecting changes in pitch, roll, and yaw	16
Figure 1.5: Revenue and grow rate forecast for X-by-wire systems in Europe [17] .....	18
Figure 1.6: Powertrain technologies.....	19
Figure 1.7: Typical Battery Management System diagram [6] .....	21
Figure 1.8: Automotive entertainment system .....	22
Figure 1.9: 12V system compared to 42V system [9] .....	24
Figure 2.1: Block diagram of the USI proposed in [22].....	30
Figure 2.2: UMSI chip and optional external component .....	31
Figure 2.3: Platform abstraction and design flow .....	32
Figure 2.4: applications for MEMS in automotive.....	34
Figure 2.5: Vibrating ring gyro .....	35
Figure 2.6: Capacitive MEMS accelerometer .....	36
Figure 2.7: AMR with magnetic field (a), Wheatstone bridge configuration (b), output characteristic (c) .....	37
Figure 2.8: Spin valve GMR (Wheatstone bridge configuration) .....	38
Figure 2.9: cross section view of BCD6 process without and with heavily doped N <sup>+</sup> buried layer .....	41
Figure 2.10: cross section of the RF LDMOS realized in BCD6.....	42
Figure 2.11: class AB audio amplifier in BCD5 .....	43
Figure 2.12: mixed-signal circuit to drive an electric motor in BCD5 .....	43
Figure 2.13: ISIF block diagram .....	44
Figure 2.14: Analog input channel .....	45

Figure 2.15: LEON and digital hardware IPs .....	46
Figure 2.16: software PLL implemented on a inertial MEMS sensor	48
Figure 2.17: ISIF layout and chip .....	48
Figure 2.18: dual axis accelerometer prototypization .....	49
Figure 3.1: Gate-charge ( $Q_G$ ) versus gate-to-source voltage ( $V_{GS}$ ) ....	58
Figure 3.2: Simplified diagram of a typical gate driver.....	59
Figure 3.3: Half-bridge driver schematic .....	60
Figure 3.4: Half-bridge system and typical PWM driving signal .....	61
Figure 3.5: Block diagram of the digital controller .....	65
Figure 3.6: PWM output signals .....	66
Figure 3.7: DAC slewrate output timing.....	67
Figure 3.8: layout of the analog section of the gate driver .....	68
Figure 3.9: Fast transition of the half bridge.....	69
Figure 3.10: Slow transition of the half-bridge.....	70
Figure 3.11: Current delivered by the driver to the IRF7309 Pch gate and IRF7309 Pch $V_{GS}$ transition .....	70
Figure 3.12: head-up display and mobile beamer .....	71
Figure 3.13: simplified block diagram of the new digital platform....	73
Figure 3.14: simplified block diagram of the new analog platform....	74
Figure 3.15: layout of two micromirrors implementing DMD chip [61] .....	78
Figure 3.16: DMD application [63] .....	78
Figure 3.17: magnetically actuated micromirror.....	79
Figure 3.18: thermal actuated micromirror [70] .....	80
Figure 3.19: piezoelectric actuated micromirror [67] .....	80
Figure 3.20: AVC on the top and SVC on the bottom [71] .....	81
Figure 3.21: ISIT scanning micromirror layout .....	82
Figure 3.22: optical scan angle versus pressure and driving voltage..	83
Figure 3.23: diagram of the actuator.....	85
Figure 3.24: driving voltage to actuate the micromirror.....	86
Figure 3.25: HV driver alternative architectural solutions .....	87
Figure 3.26: schematic of the HV driver.....	87
Figure 3.27: First stage .....	90
Figure 3.28: Second stage .....	91
Figure 3.29: second stage biasing circuit.....	92
Figure 3.30: Resistor-Averaged CMFB [74] .....	94
Figure 3.31: CMFB of the HV driver .....	94
Figure 3.32: CMFB of the driver (a) and implementation of the programmable resistor (b) .....	96
Figure 3.33: HV driver programmable biasing circuit.....	97

Figure 3.34: power down circuitry example.....	97
Figure 3.35: clamp diode to protect M15, M15* and M23 .....	98
Figure 3.36: complete OPA schematic .....	100
Figure 3.37: $V_{IO}$ statistical distribution .....	105
Figure 3.38: frequency spectrum of the differential output voltage on a simulation extracted from the Montecarlo.....	106
Figure 3.39: THD statistical analysis .....	106
Figure 3.40: PSRR statistical analysis.....	107
Figure 3.41: HV driver layout .....	108

# INDEX OF TABLES

Table 1.1: Automotive electronics temperature and vibration extremis .....	25
Table 2.1: main BCD6 and BCD8 characteristics .....	44
Table 3.1: Advantages and disadvantages of MOEMS [59] .....	76
Table 3.2: ISIT micromirror characteristics.....	84
Table 3.3: resistors size .....	88
Table 3.4: CMFB programmability .....	88
Table 3.5: dirver specifications.....	89
Table 3.6: resistors and $V_{OCM}$ .....	95
Table 3.7: transistors size.....	99
Table 3.8: design critical OPA design parameters.....	102
Table 3.9: Some parameters over corners.....	104